

Light Emitting Diode

18 K

Description

• Size: 2.1*2.4mm with 1.8mm lens.

Emitting color: Ultra red.

Lens color: Water clear.

Lead type: Axial lead

Main Features

• Instant light less than 100ns turn on time.

Compatible with infrared and vapor phase reflow solder process.

Compatible with automatic placement equipment.

Superior resistance to moisture.

Cool beam, safe to touch.

Reliable and rugged.

Pb-Free.

Wide viewing angle.

Absolute Maximum Rating TA=25°C								
Parameter	Symbol	Rating	Unit	Notice				
Power Dissipation	Pd	85	mW					
DC Forward Current	lF	30	mA					
Pulse Forward Current	IF (PEAK)	100	mA	Duty 1/10 @ 1KHz				
Reverse Voltage	VR	5	V	Under 100uA				
Operating Temperature Range	T OPR	-20 to +80	°C					
Storage Temperature Range	Tstg	-25 to +85	°C	Humidity should be under 50%				
Lead Soldering Temperature	T SOL	260 +/-5	°C	4mm (0.157") from mold body Les then 5 Second				

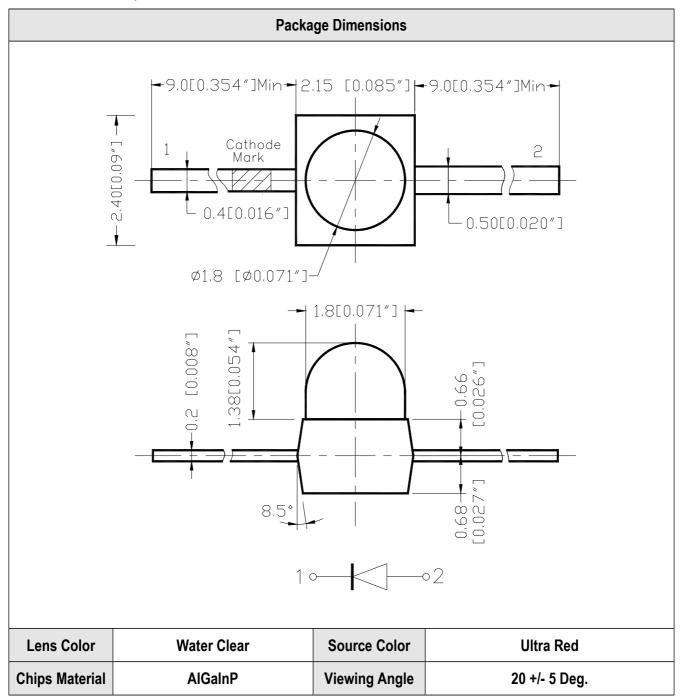
Part Selection Electrical / Optical Characteristics At TA-25°C										
Characteristic	Symbol	Test Cond	dition Min	. Тур.	Max.	Unit.				
Forward Voltage	VF	IF =20	mA 1.80	2.05	2.40	V				
Reverse Current	lR	VR =5V	_	-	10	uA				
Luminous Intensity (Note 1)	lv	IF =20	mA 600	1500	3000	mcd				
Peak Emission Wavelength	λр	IF =20	mA 635	640	645	nm				
Spectral Line Half Width	Δλ	IF =20	mA 18	20	23	nm				
Dominant Wavelength (Note 2)	λd	IF =20	mA 625	630	635	nm				

Note:

- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
- 2. The dominant wavelength (λd) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 3. Forward voltage measurement allowance is +/-0.1V



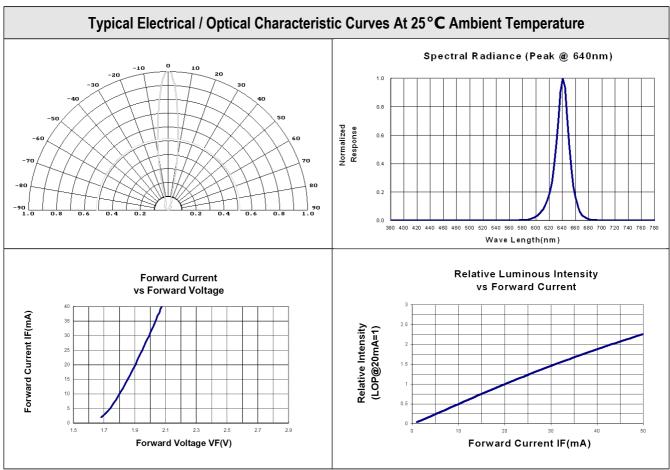
4. Luminous intensity measurement allowance +/-10%



NOTES:

- All dimensions are in millimeters (inches).
- Tolerance is ±0.25 mm (.010") unless otherwise noted.
- Protruded resin under flange is 1.0mm(.04") max
- Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.





NOTE:

- ullet $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- Clean only in isopropanol, ethanol, Freon TF (or equivalent).
- When using this product, Please observe the absolute maximum rating and the instructions for use outlined from use of the
 product, which does not comply with the absolute maximum rating and the instructions included in these specification sheet.
- If forming is required, it must be done before soldering. Form pin leads by securing under 5mm from body and bedding with radio pliers or the equivalent to avoid pressure on resin. When the LED is mounted into a P.C.board, pitch spacing should be aligned to prevent cause any stress to the resin. Any unsuitable stress applied to resin may break bonding wire in LED, which will cause failure.

Over-current-proof:

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

Parallel connection:

Customer must apply series resistor in each LED under parallel connection. Otherwise VF difference will cause LED array lighting not even.

- Check at a distance of 30cm from the LED to the eye defects.
- Q.A Outgoing inspection standard:

Major Defect 0.65 A.Q.L. Minor Defect 1.5 A.Q.L

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